

A B C D E

1
2
3
4

RECOMMENDED PCB LAYOUT(PCB THICKNESS: 1.6mm)
COMPONENT SIDE VIEW(TOLERANCE: ±0.05)

A TYPE B TYPE C TYPE

1.MATERIAL:
1.1 INSULATOR: PA66, UL94V-2
INSULATOR COLOR: NATURAL
1.2 CONTACT: BRASS
2.FINISH:
2.1 CONTACT: TIN PLATED OVER
NICKEL UNDERPLATED OVERALL.
3.NOTES:
3.1 THIS COMPONENT AND ITS HOMOGENEOUS
SUBCOMPONENTS ARE RoHS COMPLIANT.
3.2 RESISTANCE TO SOLDERING HEAT: 265°C FOR 5 SECONDS,
AND ONLY FOR WAVE SOLDERING PROCESS.
(THE POSTS & BOARDLOCK WILL BE MELTING)

4. ORDER INFORMATION:
XTB-WF3 X 3QCA1T-1 XX A-T01
PRODUCT TYPE: A = A TYPE B = B TYPE C = C TYPE
NO. OF CONTACTS:
102: 1* 02=2PINS
103: 1* 03=3PINS
104: 1* 04=4PINS
105: 1* 05=5PINS
106: 1* 06=6PINS

5. OPTION:

CONTACTS	DIM.A	DIM.B
2	4.20	9.60
3	8.40	13.80
4	12.60	18.00
5	16.80	22.20
6	21.00	26.40

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REV.	DESCRIPTION	ECN NO.	NAME	DATE
AO	NEW RELEASE		Milo	Aug.03.2011

DIM. TOL.
X
X.X ±0.30
X.XX ±0.25
X.XXX ±0.15
GENERAL ANGLE: ±3°

TITLE: WAFER WIRE TO BOARD R/A DIP TYPE
DWG. NO.: C-WF3X3QCA1T-1XXA
PART NO.: XTB-WF3X3QCA1T-1XXA-T01
UNIT: mm SCALE: none SHEET: 1 OF 1 DWG. SIZE: A4 LAYER: CR126

XMULTIPLE
RFQ NO.: Q1107157

REVISIONS ARTICLE: CPC-CN-002-C